

SOT1302-1

plastic fine-pitch ball grid array package; 196 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA196
Package type industry code	FBGA196
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	22-2-2011

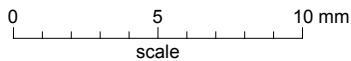
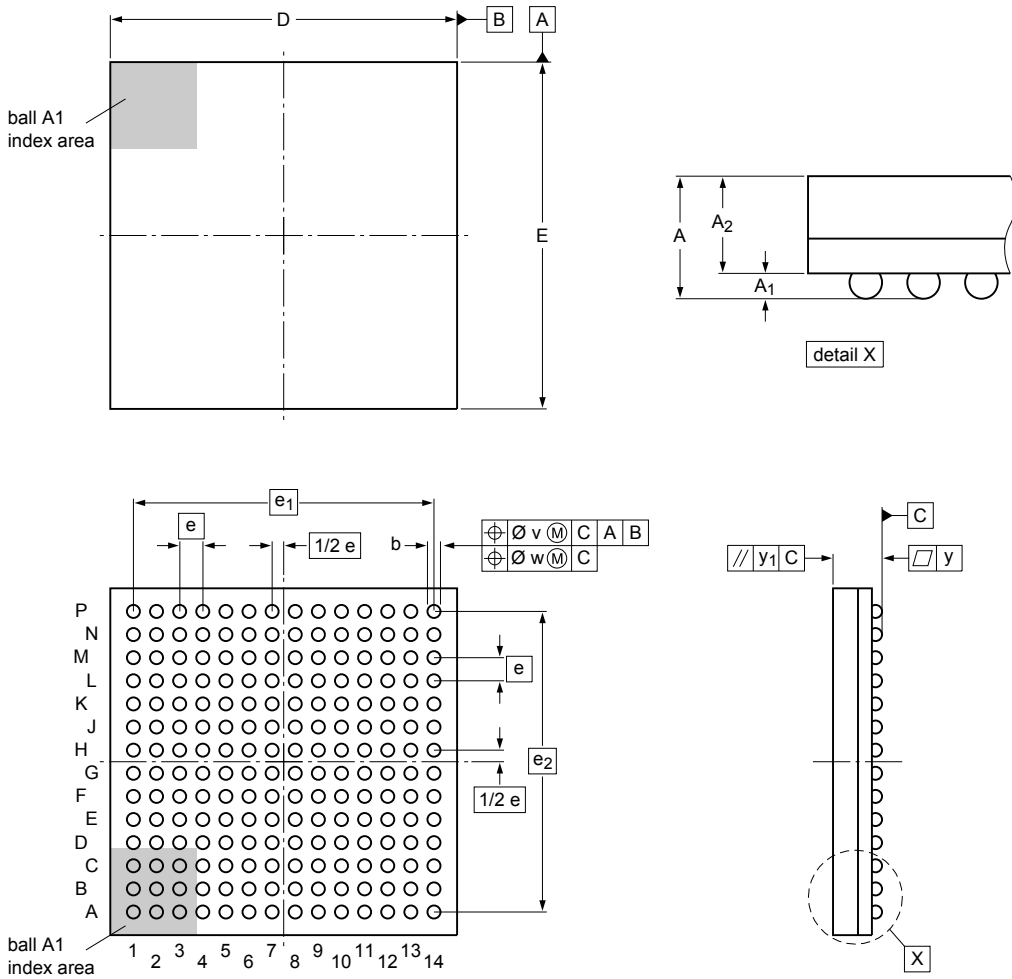
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	1.55	-	1.7	1.8	mm
A ₂	package height	1.25	-	1.35	1.4	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	196	-	



2. Package outline

FBGA196: plastic fine-pitch ball grid array package; 196 balls; body 12 x 12 x 1.35 mm SOT1302-1



Dimensions

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
max	1.80	0.40	1.40	0.50	12.1	12.1							
mm nom	1.70	0.35	1.35	0.45	12.0	12.0	0.8	10.4	10.4	0.15	0.08	0.12	0.1
min	1.55	0.30	1.25	0.40	11.9	11.9							

sot1302-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1302-1		MO-205			11-02-21 11-02-22

Fig. 1. Package outline FBGA196 (SOT1302-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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